



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





### HIGH PERFORMANCE THERMAL GREASE

Tgrease<sup>™</sup> 300X is a silicone-based thermal grease for use in high performance CPU's and GPU's. Tgrease<sup>™</sup> 300X has a high thermal conductivity of 3.0 W/mK and superior wetting characteristics, resulting in a very low thermal resistance and excellent long term reliability. Tgrease<sup>™</sup> 300X has been formulated not to sag or drip with a high thixotropic index for ease of application and reliability.

### FEATURES AND BENEFITS

- Low thermal resistance
- Excellent long term stability
- RoHS compliant
- Resists pump out through novel gel technology
- Available in 1kg (quart container), custom syringes

### APPLICATIONS

- Computer CPUs and GPUs
- Telecommunications infrastructure
- Network Hardware
- Automotive electronics
- Consumer electronics

Typical Properties		Test Method
Color	Gray	Visual
Density	2.87 g/cc	Helium Pycnometer
Viscosity	400,000 cP	Brookfield DV-II Helipath Spindle T-F 20 RPMs
Thixotropic Index	3.35	Brookfield Viscometer RPMs
Thermal Resistance @ 50 psi @ 344.7 kPa	0.013°C-in <sup>2</sup> /W 0.084°C-cm <sup>2</sup> /W	ASTM D5470 (modified)
Thermal Conductivity	3.0 W/mk	Hot disk thermal constants analyzer
Bond Line Thickness	0.001 in, 25 microns	

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

### STORAGE

Store between 15 and 45°C and a maximum humidity of 50%. Do not store in freezer or refrigerator below 5°C.

### APPLICATION

Screen print using a mesh of 61 threads per inch (TPI) or less is recommended for easiest application, however the grease has been successfully applied using up to a 140 TPI mesh (The higher the number = smaller mesh opening). If applying from a can, mix can well prior to use. Dispense via syringe or cartridge by hand or mechanically.

Americas: +1.800.323.3757  
LHP.Sales@lairdtech.com  
Europe: +46.8.555.722.00  
LHP.Sales@lairdtech.com  
Asia: +86.10.5933.3682  
LHP-ChinaSales@lairdtech.com

[www.lairdtech.com](http://www.lairdtech.com)

THR-DS-Tgrease-300X 0613

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